



Material Content Data Sheet



Sales Product Name		BSZ120P03NS3E G		Issued		26. September 2017		
MA#		MA001336248						
Package		PG-TSDSON-8-2		Weight*		38.42 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.346	3.50	3.50	35025	35025
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		55	
	non noble metal	zinc	7440-66-6	0.008	0.02		218	
	non noble metal	iron	7439-89-6	0.168	0.44		4364	
wire	non noble metal	copper	7440-50-8	6.808	17.72	18.19	177201	181838
	non noble metal	copper	7440-50-8	0.050	0.13	0.13	1309	1309
	encapsulation	organic material	carbon black	1333-86-4	0.035	0.09		901
	plastics	epoxy resin	-	1.783	4.64		46416	
	inorganic material	silicondioxide	60676-86-0	15.495	40.34	45.07	403327	450644
leadfinish	non noble metal	tin	7440-31-5	0.387	1.01	1.01	10077	10077
plating	noble metal	silver	7440-22-4	0.963	2.51	2.51	25056	25056
solder	noble metal	silver	7440-22-4	0.037	0.10		972	
	non noble metal	tin	7440-31-5	0.030	0.08		777	
	non noble metal	lead	7439-92-1	1.426	3.71	3.89	37123	38872
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		28	
	non noble metal	zinc	7440-66-6	0.004	0.01		112	
	non noble metal	iron	7439-89-6	0.086	0.22		2244	
heat sink CLIP	non noble metal	copper	7440-50-8	3.501	9.11	9.34	91134	93518
	inorganic material	phosphorus	7723-14-0	0.002	0.00		49	
	non noble metal	zinc	7440-66-6	0.008	0.02		196	
	non noble metal	iron	7439-89-6	0.151	0.39		3928	
	non noble metal	copper	7440-50-8	6.127	15.95	16.36	159488	163661
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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